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## **INDEX**

**Opening and Keynotes** 

Integrated passice devices and silicon interposes (Abstract)
Investigating in Intellectual Assets (Abstract)
Flip Chip Technology
Temperature Cycling and Constant Humidity Test for Flip Chip Joints using Pre-Aged ACF
Advanced Flip Chip for Imaging Devices
Au Stud Bump Optimization for Anisotropic Conductive Adhesives Interconnets
Advanced Technologies and Applications
LED device developing trend & LED products for understanding LED packaging
3D Computational Fluid Dynamics Simulation of Carbon Nanotubes Based Microchannels On-Chip Cooler
Room temperature soldering of difficult components
Reliability Concerns
Managing the Reliability Time-bombs of Modern Electronics and Photonics
The reliability challenges of QFN packaging
Polymers and Adhesives
Changes in chemical structures of commercial  ACF after thermal cyckling and humidity testing

Particle distribution in screen printed and dispensed ACF interconnections
3D Technology
Through Silicon Vias Integration in 3D Integrated Passive Technology
Die with TSV Packaging from Japan
Encapsulations, Bonding and Substrates
HB-LED Cavity Encapsulation (Abstract)
Coreless substrates – a new approach
Gold to Gold Thermosonic Bonding Characterization of Bonding Parameters
Moisture effects on the performance of RFID tags with ACA joints
Advanced Methods and Materials
Hydraulic modelling of EMC screens and fans for telecommunication cabinets: state of the art
Acoustic Matching Layer for High Frequency Transducers made by Anisotropic Wet Etching of Silicon
Comparison of ceramic multilayer technology for RF integration of CTCC/LTCC (Abstract)
Temperature and Humidity Testing of Ridig-Flex ACA Heat Seal Attachments